

General Description

OST30N65KTXF uses advanced Oriental-Semi's patented Trident-Gate Bipolar Transistor (TGBT™) technology to provide extremely low $V_{CE(sat)}$, low gate charge, and excellent switching performance. This device is suitable for mid to high range switching frequency converters.

Features

- Advanced TGBT™ technology
- Excellent conduction and switching loss
- Excellent stability and uniformity
- Fast and soft antiparallel diode



Applications

- Induction converters
- Uninterruptible power supplies

Key Performance Parameters

Parameter	Value	Unit
$V_{CES, min}$ @ 25 °C	650	V
Maximum junction temperature	175	°C
I_C , pulse	120	A
$V_{CE(sat), typ}$ @ $V_{GE}=15$ V	1.65	V
Q_g	44	nC

Marking Information

Product Name	Package	Marking
OST30N65KTXF	TO263	OST30N65KTX

Package & Pin Information



Absolute Maximum Ratings at $T_{vj}=25\text{ }^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Collector emitter voltage	V_{CES}	650	V
Gate emitter voltage	V_{GES}	± 20	V
Transient gate emitter voltage, $T_P \leq 10\text{ }\mu\text{s}, D < 0.01$		± 30	V
Continuous collector current ¹⁾ , $T_c=25\text{ }^{\circ}\text{C}$	I_c	42	A
Continuous collector current ¹⁾ , $T_c=100\text{ }^{\circ}\text{C}$		30	A
Pulsed collector current ²⁾ , $T_c=25\text{ }^{\circ}\text{C}$	$I_{C, \text{pulse}}$	120	A
Diode forward current ¹⁾ , $T_c=25\text{ }^{\circ}\text{C}$	I_F	42	A
Diode forward current ¹⁾ , $T_c=100\text{ }^{\circ}\text{C}$		30	A
Diode pulsed current ²⁾ , $T_c=25\text{ }^{\circ}\text{C}$	$I_{F, \text{pulse}}$	120	A
Power dissipation ³⁾ , $T_c=25\text{ }^{\circ}\text{C}$	P_D	250	W
Power dissipation ³⁾ , $T_c=100\text{ }^{\circ}\text{C}$		125	W
Operation and storage temperature	T_{stg}, T_{vj}	-55 to 175	$^{\circ}\text{C}$
Short circuit withstand time $V_{GE}=15\text{ V}, V_{CC} \leq 400\text{ V}$ Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0\text{ S}$ $T_{vj}=150\text{ }^{\circ}\text{C}$	t_{sc}	5	μs

Thermal Characteristics

Parameter	Symbol	Value	Unit
IGBT thermal resistance, junction-case	$R_{\theta JC}$	0.6	$^{\circ}\text{C/W}$
Diode thermal resistance, junction-case	$R_{\theta JC}$	1.8	$^{\circ}\text{C/W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	40	$^{\circ}\text{C/W}$

Electrical Characteristics at $T_{vj}=25\text{ }^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Collector-emitter breakdown voltage	$V_{(BR)CES}$	650			V	$V_{GE}=0\text{ V}$, $I_c=0.5\text{ mA}$
Collector-emitter saturation voltage	$V_{CE(sat)}$		1.65	2.0	V	$V_{GE}=15\text{ V}$, $I_c=30\text{ A}$, $T_{vj}=25\text{ }^{\circ}\text{C}$
			1.85		V	$V_{GE}=15\text{ V}$, $I_c=30\text{ A}$, $T_{vj}=125\text{ }^{\circ}\text{C}$
			1.95			$V_{GE}=15\text{ V}$, $I_c=30\text{ A}$, $T_{vj}=175\text{ }^{\circ}\text{C}$
Gate-emitter threshold voltage	$V_{GE(th)}$	4.0	5.0	6.0	V	$V_{CE}=V_{GE}$, $I_D=0.5\text{ mA}$
Diode forward voltage	V_F		1.7	2.0	V	$V_{GE}=0\text{ V}$, $I_F=30\text{ A}$, $T_{vj}=25\text{ }^{\circ}\text{C}$
			1.6			$V_{GE}=0\text{ V}$, $I_F=30\text{ A}$, $T_{vj}=125\text{ }^{\circ}\text{C}$
			1.5			$V_{GE}=0\text{ V}$, $I_F=30\text{ A}$, $T_{vj}=175\text{ }^{\circ}\text{C}$
Gate-emitter leakage current	I_{GES}			100	nA	$V_{CE}=0\text{ V}$, $V_{GE}=20\text{ V}$
Zero gate voltage collector current	I_{CES}			10	μA	$V_{CE}=650\text{ V}$, $V_{GE}=0\text{ V}$

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{ies}		2445		pF	V _{GE} =0 V, V _{CE} =25 V, f=100 kHz
Output capacitance	C _{oes}		64		pF	
Reverse transfer capacitance	C _{res}		2		pF	
Turn-on delay time	t _{d(on)}		34		ns	
Rise time	t _r		44		ns	
Turn-off delay time	t _{d(off)}		88		ns	
Fall time	t _f		75		ns	
Turn-on energy	E _{on}		0.84		mJ	
Turn-off energy	E _{off}		0.34		mJ	
Turn-on delay time	t _{d(on)}		32		ns	
Rise time	t _r		19		ns	
Turn-off delay time	t _{d(off)}		120		ns	
Fall time	t _f		55		ns	
Turn-on energy	E _{on}		0.3		mJ	V _{GE} =15 V, V _{CC} =400 V, R _G =10 Ω, I _C =30 A
Turn-off energy	E _{off}		0.19		mJ	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		44		nC	V _{GE} =15 V, V _{CC} =520 V, I _C =30 A
Gate-emitter charge	Q _{ge}		25		nC	
Gate-collector charge	Q _{gc}		5		nC	

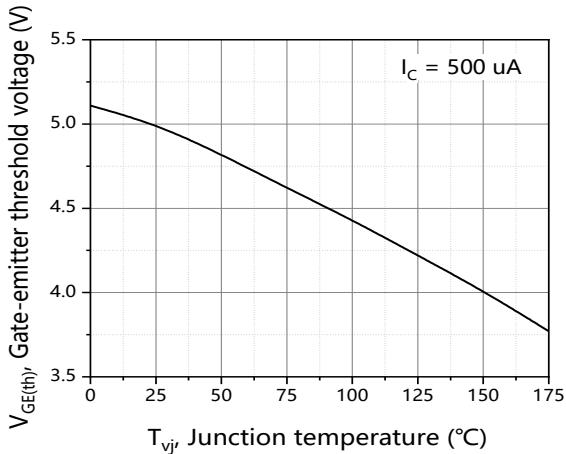
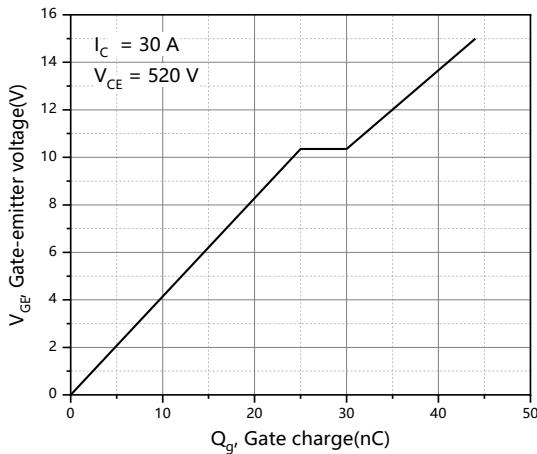
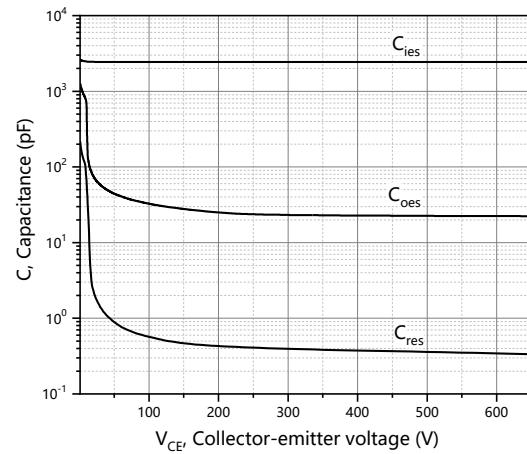
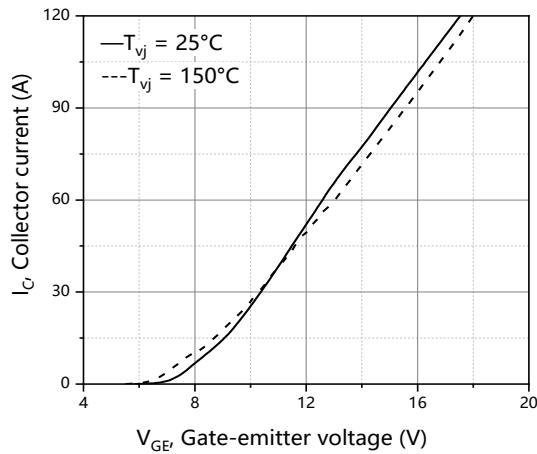
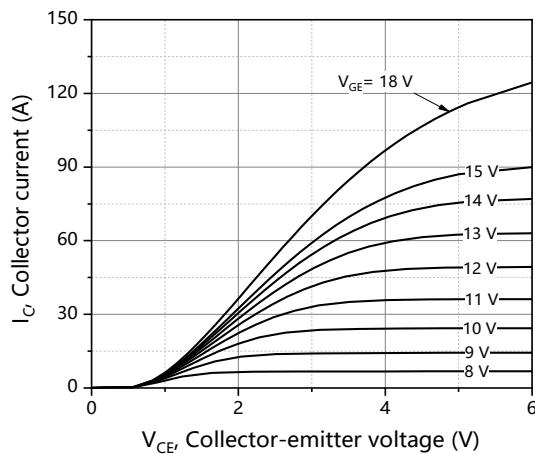
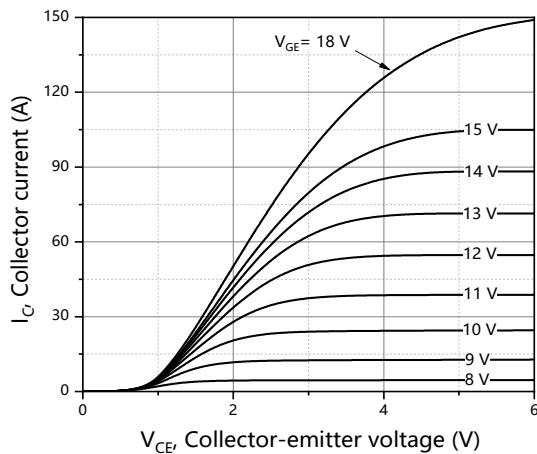
Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode reverse recovery time	t _{rr}		122		ns	V _R =400 V, I _F =30 A, dI/dt=500 A/μs T _{VJ} =25 °C
Diode reverse recovery charge	Q _{rr}		0.89		μC	
Diode peak reverse recovery current	I _{rrm}		17		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.

Electrical Characteristics Diagrams



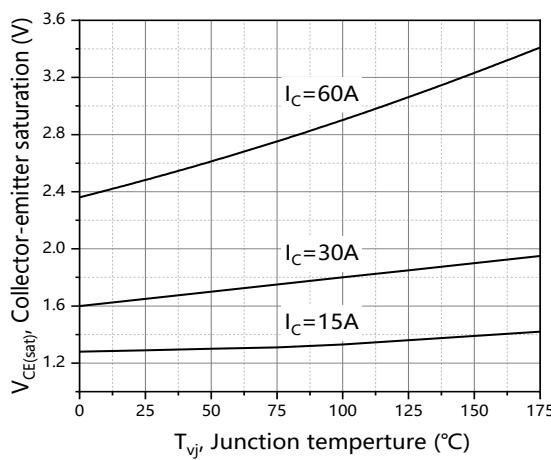


Figure 7. Typical collector-emitter voltage

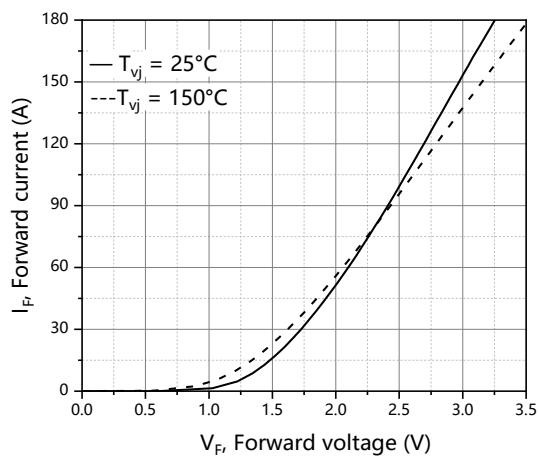


Figure 8. Forward characteristic of diode

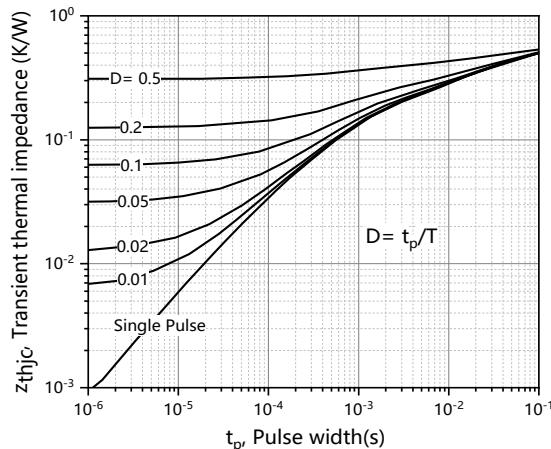


Figure 9. IGBT transient thermal impedance

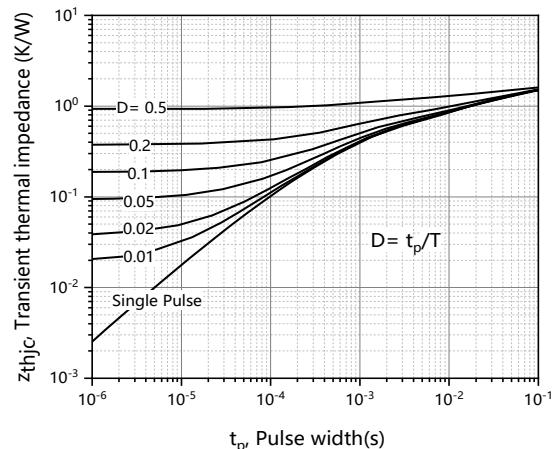
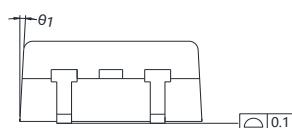
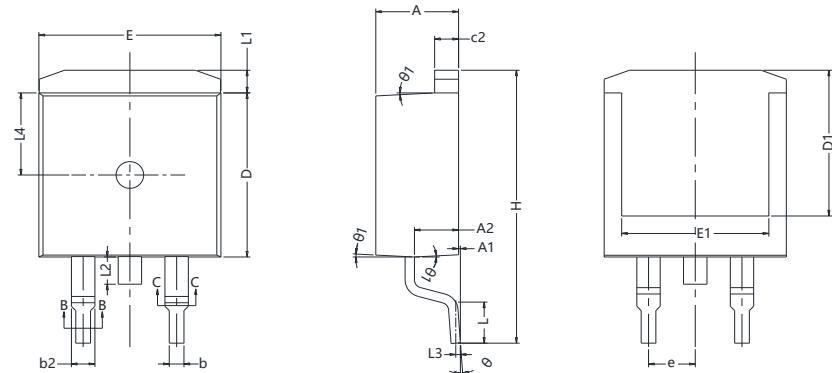


Figure 10. Diode transient thermal impedance

Package Information



Symbol	mm		
	Min	Nom	Max
A	4.40	4.50	4.60
A1	0.00	0.10	0.25
A2	2.20	2.40	2.60
b	0.76	-	0.89
b2	1.23	-	1.37
c	0.47	-	0.60
c1	0.46	0.51	0.56
c2	1.25	1.30	1.35
D	9.10	9.20	9.30
D1	8.00	-	-
E	9.80	9.90	10.00
E1	7.80	-	-
e	2.54 BSC		
H	14.90	15.30	15.70
L	2.00	2.30	2.60
L1	1.17	1.27	1.40
L2	-	-	1.75
L3	0.25 BSC		
L4	4.60 REF		
θ	0°	-	8°
θ1	1°	3°	5°

Version 1: TO263-J package outline dimension

Ordering Information

Package Type	Units/Reel	Tubes/Inner Reel	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO263-J	800	1	800	10	8000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OST30N65KTXF	TO263	yes	yes	yes

Legal Disclaimer

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